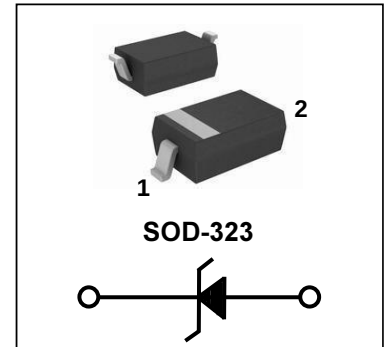


Features

- 330 Watts Peak Pulse Power per Line ($t_p = 8/20\mu s$)
- Replacement for MLV (0805)
- Protects one I/O or power line
- Low Clamping Voltage
- Working Voltage: 20V
- Low Leakage Current



IEC COMPATIBILITY (EN61000-4)

- IEC 61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 10A (8/20 μs)

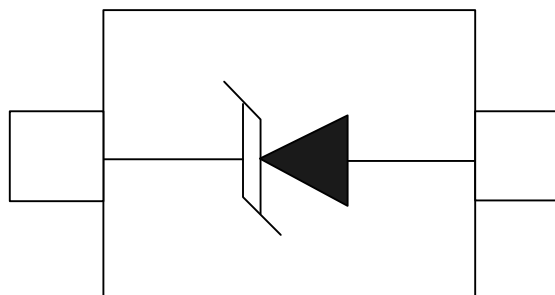
Mechanical Characteristics

- JEDEC SOD-323 package
- Molding compound flammability rating: UL 94V-0
- Marking : Marking Code
- Packaging : Tape and Reel per EIA 481
- RoHS Compliant

Applications

- Laptop Computers
- Cellular Phones
- Digital Cameras
- Personal Digital Assistants (PDAs)

Schematic & PIN Configuration



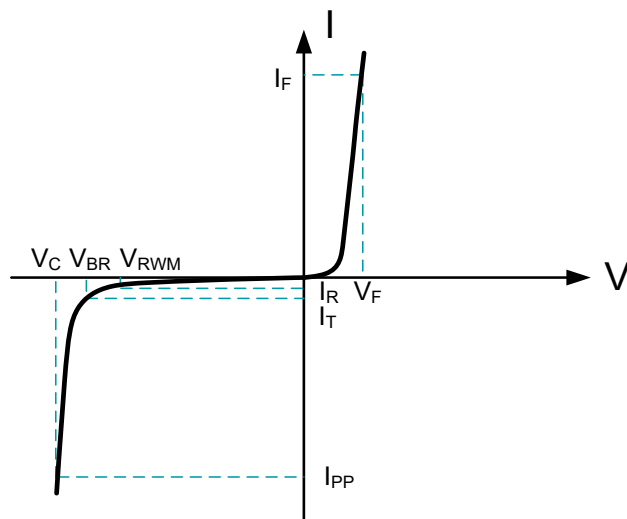
SOD-323 (Top View)

Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PP}	330	Watts
Peak Pulse Current ($t_p = 8/20\mu s$) (note1)	I_{pp}	10	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	30 30	kV
Lead Soldering Temperature	T_L	260(10seconds)	$^{\circ}C$
Junction Temperature	T_J	-55 to + 150	$^{\circ}C$
Storage Temperature	T_{stg}	-55 to + 150	$^{\circ}C$

Electrical Parameters (T=25 $^{\circ}C$)

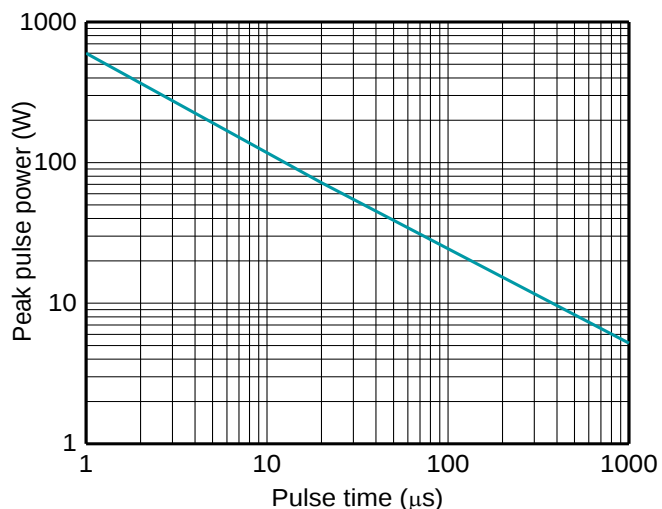
Symbol	Parameter
I_{PP}	Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_F	Forward Current
V_F	Forward Voltage @ I_F



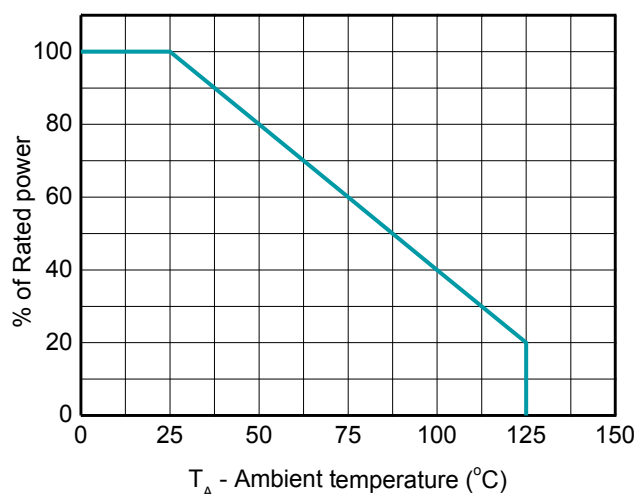
Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	V_{RWM}				20	V
Reverse Breakdown Voltage	V_{BR}	$I_T = 1mA$	21			V
Reverse Leakage Current	I_R	$V_{RWM} = 20V, T = 25^{\circ}C$			0.1	μA
Peak Pulse Current	I_{PP}	$t_p = 8/20\mu s$		10		A
Clamping Voltage	V_C	$I_{PP} = 10A, t_p = 8/20\mu s$		33		V
Junction Capacitance	C_j	$V_R = 0V, f = 1MHz$		50		pF

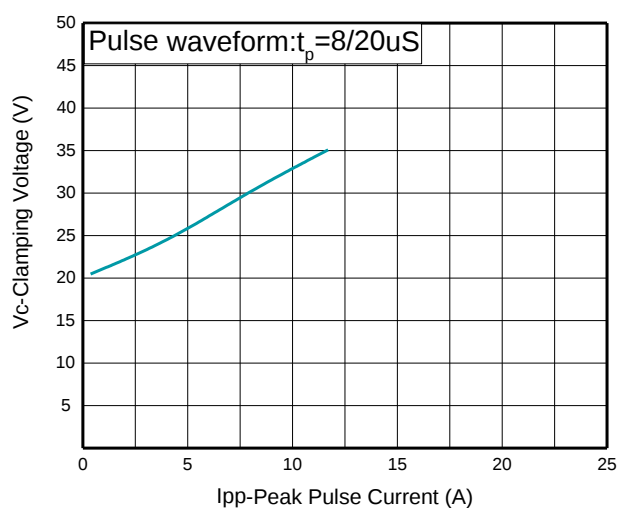
Typical Characteristics



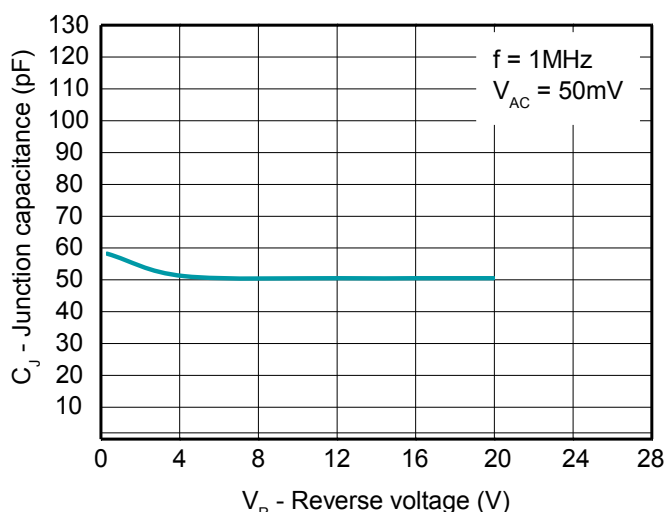
Non-repetitive peak pulse power vs. Pulse time



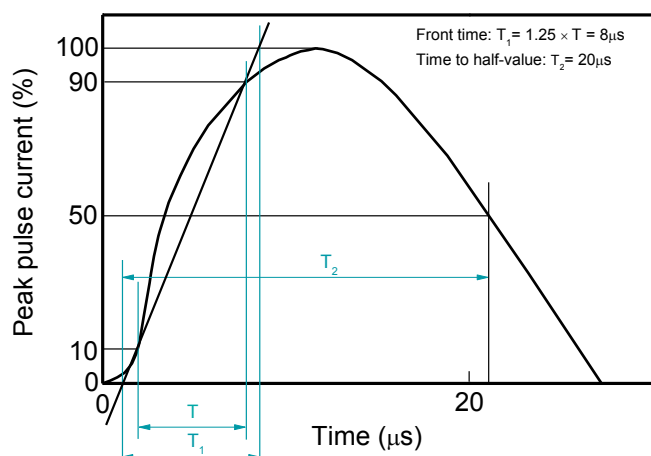
Power derating vs. Ambient temperature



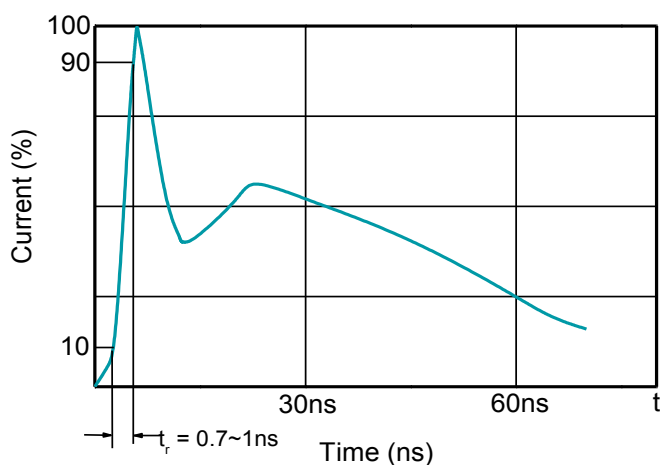
Clamping voltage vs. Peak pulse current



Capacitance vs. Reverse voltage



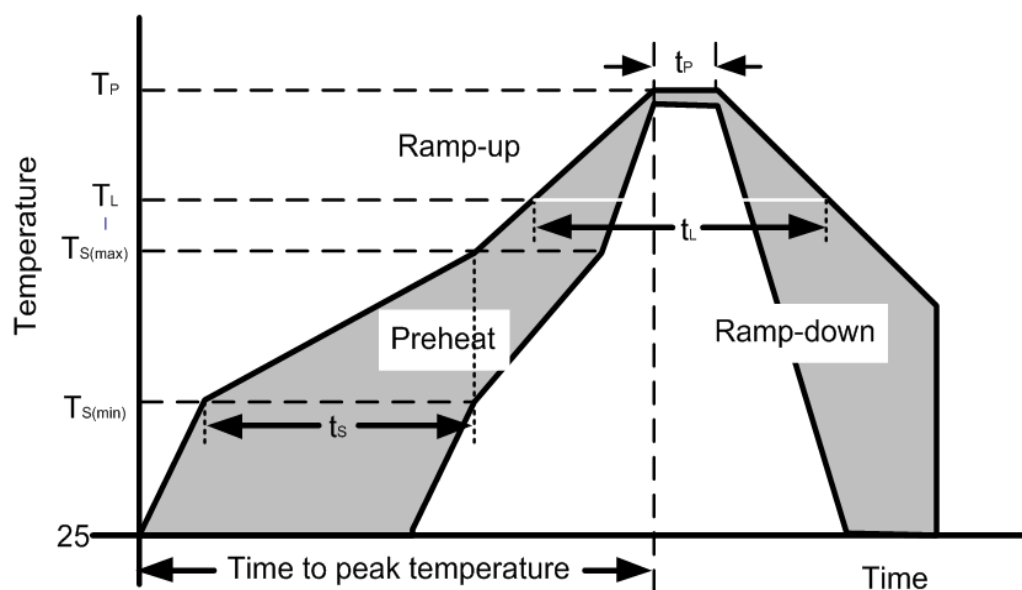
8/20μs waveform per IEC61000-4-5



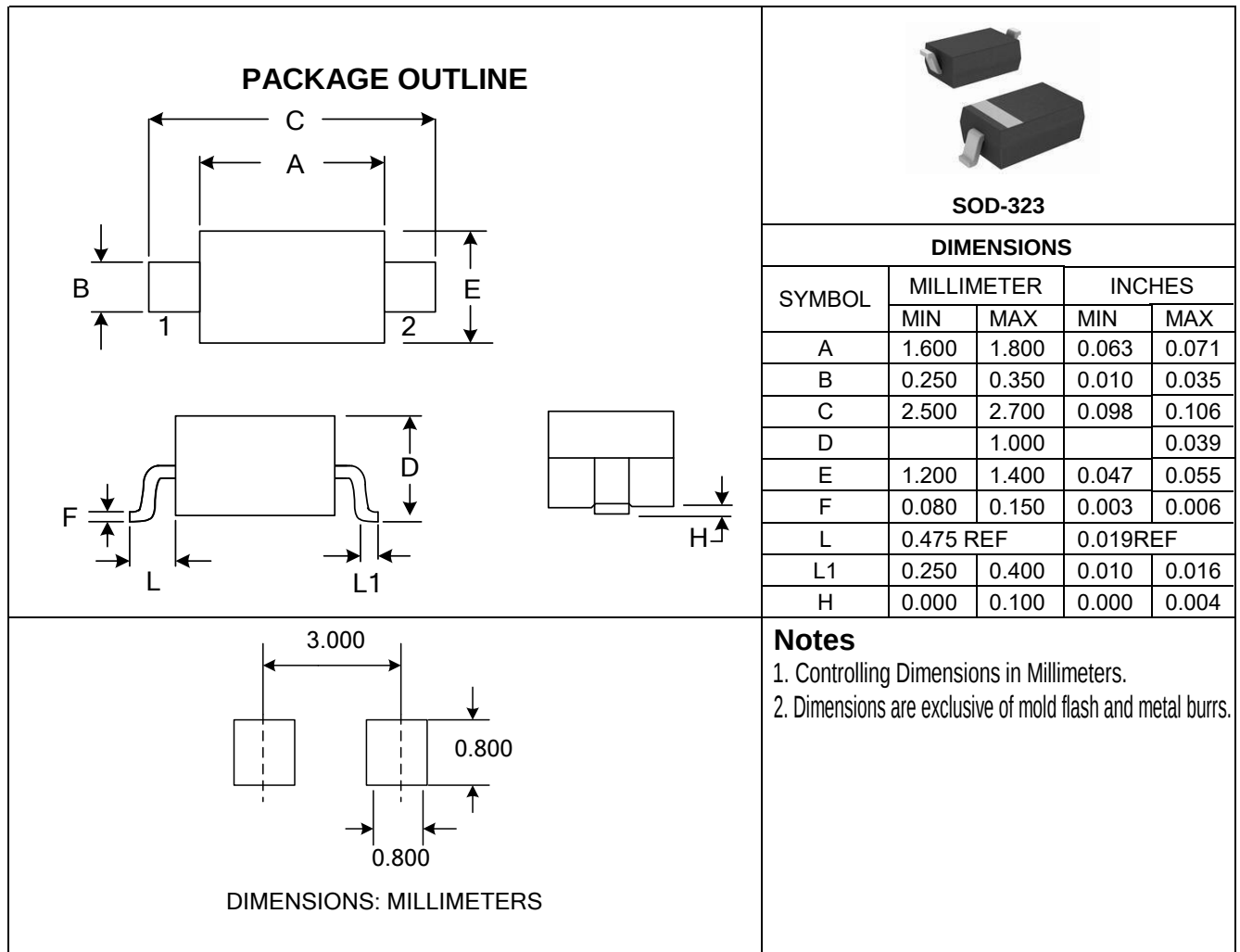
Contact discharge current waveform per IEC61000-4-2

Soldering Parameters

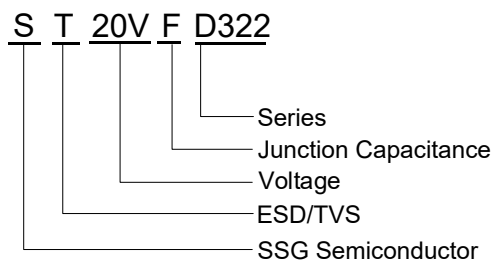
Reflow Condition		Pb – Free assembly
Pre Heat	Temperature Min ($T_{S(min)}$)	150°C
	Temperature Max ($T_{S(max)}$)	200°C
	Time (min to max) (t_s)	60 – 190 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
$T_{S(max)}$ to T_L —Ramp-up Rate		5°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		260+0/-5 °C
Time within actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		280°C



Outline Drawing – SOD-323



Part Numbering System



Device	Package	Shipping	MarKing	Parameter
ST20VFD322	SOD-323	3000/Tape&Reel	20 *	20 = Product Code * = Device Code